



FQD12N20L / FQU12N20L

200V LOGIC N-Channel MOSFET

General Description

These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency switching DC/DC converters, switch mode power supply, motor control.

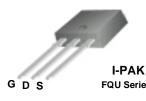
Features

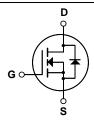
- 9.0A, 200V, $R_{DS(on)} = 0.28\Omega @V_{GS} = 10 V$
- Low gate charge (typical 16 nC)
- Low Crss (typical 17 pF)
- Fast switching
- 100% avalanche tested
- · Improved dv/dt capability
- Low level gate drive requirement allowing direct opration from logic drivers

 OFFREE

 OFF
- · RoHS Compliant







Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter		FQD12N20L / FQU12N20L	Units
V _{DSS}	Drain-Source Voltage		200	V
I _D	Drain Current - Continuous (T _C = 25°C) - Continuous (T _C = 100°C)		9.0	А
			5.7	А
I _{DM}	Drain Current - Pulsed	(Note 1)	36	Α
V _{GSS}	Gate-Source Voltage		± 20	V
E _{AS}	Single Pulsed Avalanche Energy (Note 2)		210	mJ
I _{AR}	Avalanche Current	(Note 1)	9.0	А
E _{AR}	Repetitive Avalanche Energy	(Note 1)	5.5	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)		5.5	V/ns
P _D	Power Dissipation (T _A = 25°C) *		2.5	W
	Power Dissipation (T _C = 25°C)		55	W
	- Derate above 25°C		0.44	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C
T _L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C

Thermal Characteristics

Symbol	Parameter	Тур	Max	Units
R _{0JC} Thermal Resistance, Junction-to-Case			2.27	°C/W
$R_{\theta JA}$	R _{0JA} Thermal Resistance, Junction-to-Ambient *		50	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		110	°C/W

* When mounted on the minimum pad size recommended (PCB Mount)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Cha	racteristics					
BV _{DSS}	Drain-Source Breakdown Voltage $V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		200			V
ΔBV _{DSS} / ΔΤ _J	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C		0.14		V/°C
I _{DSS}		V _{DS} = 200 V, V _{GS} = 0 V		-	1	μΑ
	Zero Gate Voltage Drain Current	V _{DS} = 160 V, T _C = 125°C			10	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 20 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -20 V, V _{DS} = 0 V			-100	nA
On Cha	racteristics					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	1.0		2.0	V
R _{DS(on)}	Static Drain-Source $V_{GS} = 10 \text{ V}, I_D = 4.5 \text{ A}$			0.22	0.28	Ω
	On-Resistance	On-Resistance $V_{GS} = 5 \text{ V}, I_D = 4.5 \text{ A}$		0.25	0.32	52
9 _{FS}	Forward Transconductance	$V_{DS} = 30 \text{ V}, I_{D} = 4.5 \text{ A}$ (Note 4)		11.6		S
C _{iss}	Input Capacitance Output Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz		830 120	1080 155	pF pF
C _{rss}	Reverse Transfer Capacitance	<u> </u>		17	22	pF
Switchi	ng Characteristics					
t _{d(on)}	Turn-On Delay Time	V _{DD} = 100 V, I _D = 11.6 A,		15	40	ns
t _r	Turn-On Rise Time	$V_{DD} = 100 \text{ V}, I_{D} = 11.6 \text{ A},$ $R_{G} = 25 \Omega$		190	390	ns
t _{d(off)}	Turn-Off Delay Time			60	130	ns
t _f	Turn-Off Fall Time	(Note 4, 5)		120	250	ns
Q _g	Total Gate Charge	V _{DS} = 160 V, I _D = 11.6 A,		16	21	nC
Q _{gs}	Gate-Source Charge	$V_{GS} = 5 \text{ V}$		2.8		nC
Q _{gd}	Gate-Drain Charge	(Note 4, 5)		7.6		nC
Drain-S	ource Diode Characteristics ar	nd Maximum Ratings				
I _S	Maximum Continuous Drain-Source Diode Forward Current				9.0	Α
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current			1	36	Α
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 9.0 A		-	1.5	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _S = 11.6 A,		128		ns
		dl / dt = 100 A/up (Note 4)				

- Notes: Notes: 1. Repetitive Rating: Pulse width limited by maximum junction temperature 2. L = 3.9mH, I_{AS} = 9.0A, V_{DD} = 50V, R_{C} = 25 Ω , Starting T_{J} = 25°C 3. I_{SD} \leq 11.6A, $di/dt \leq$ 300A/μs, V_{DD} \leq BV $_{DSS}$, Starting T_{J} = 25°C 4. Pulse Test: Pulse width \leq 300 μ , Duty cycle \leq 2% 5. Essentially independent of operating temperature

Typical Characteristics

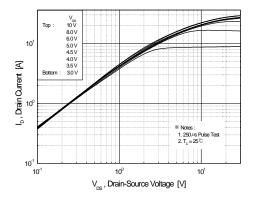


Figure 1. On-Region Characteristics

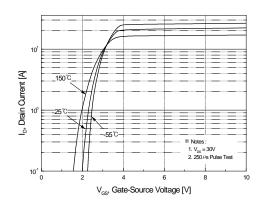


Figure 2. Transfer Characteristics

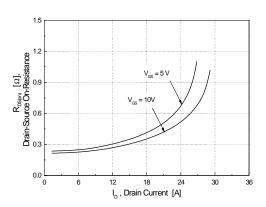


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

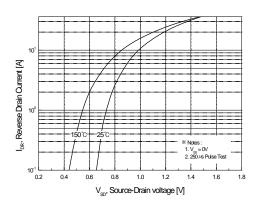


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

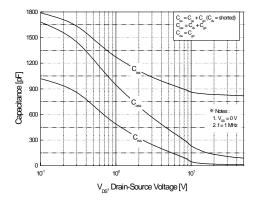


Figure 5. Capacitance Characteristics

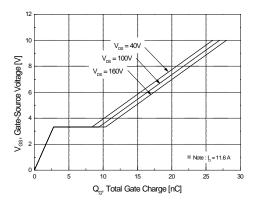
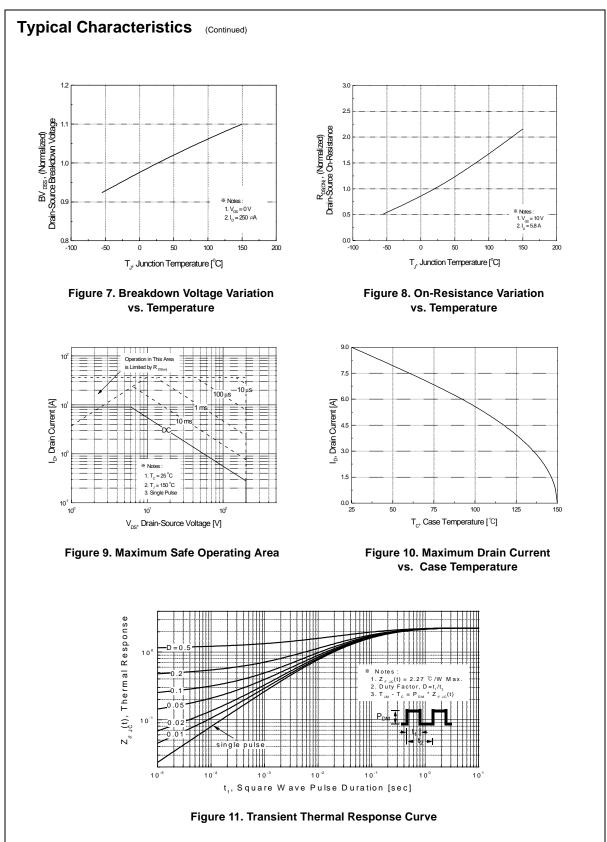


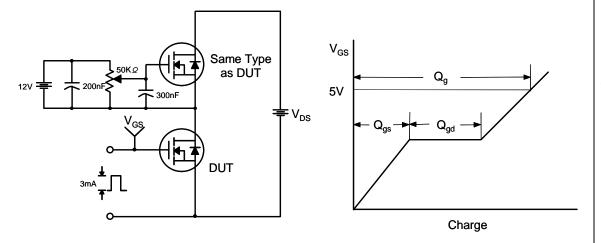
Figure 6. Gate Charge Characteristics

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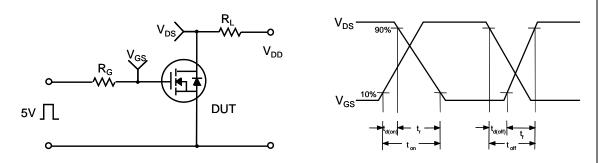


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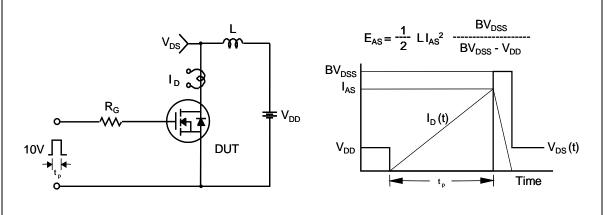
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms



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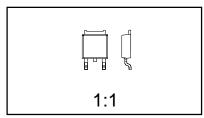
Peak Diode Recovery dv/dt Test Circuit & Waveforms DUT I_{SD o} Driver Same Type as DUT V_{DD} • dv/dt controlled by R_G • I_{SD} controlled by pulse period Gate Pulse Width V_{GS} Gate Pulse Period 10V (Driver) I_{FM} , Body Diode Forward Current \mathbf{I}_{SD} di/dt (DUT) I_{RM} **Body Diode Reverse Current** V_{DS} (DUT) Body Diode Recovery dv/dt **Body Diode** Forward Voltage Drop

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Mechanical Dimensions

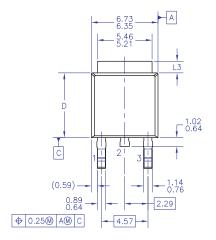
TO-252 (DPAK) (FS PKG Code 36)



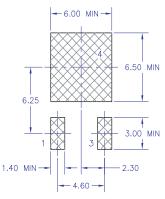


Scale 1:1 on letter size paper Dimensions shown below are in: millimeters

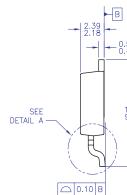
Part Weight per unit (gram): 0.33

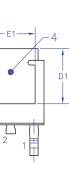


SEE NOTE D



LAND PATTERN RECOMMENDATION

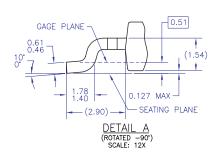




NOTES: UNLESS OTHERWISE SPECIFIED

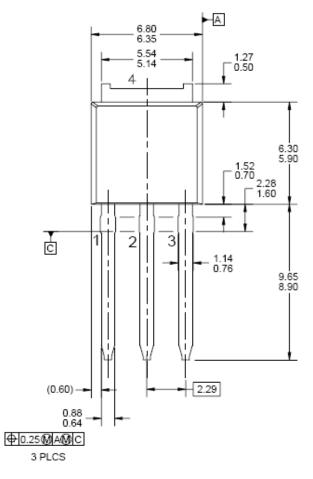
- ALL DIMENSIONS ARE IN MILLIMETERS.
 THIS PACKAGE CONFORMS TO JEDEC, TO-252,
 ISSUE C, VARIATION AA & AB, DATED NOV. 1999.
- DIMENSIONING AND TOLERANCING PER
 ASME Y14.5M-1994.
 HEAT SINK TOP EDGE COULD BE IN CHAMFERED
 CORNERS OR EDGE PROTRUSION.
 DIMENSIONS L3,D,E1&D1 TABLE:

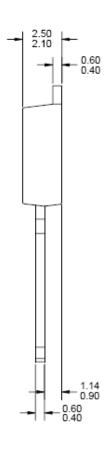
	OPTION AA	OPTION AB
L3	0.89-1.27	1.52-2.03
D	5.97-6.22	5.33-5.59
E1	4.32 MIN	3.81 MIN
D1	5.21 MIN	4.57 MIN



Mechanical Dimensions

I - PAK







Dimensions in Millimeters

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